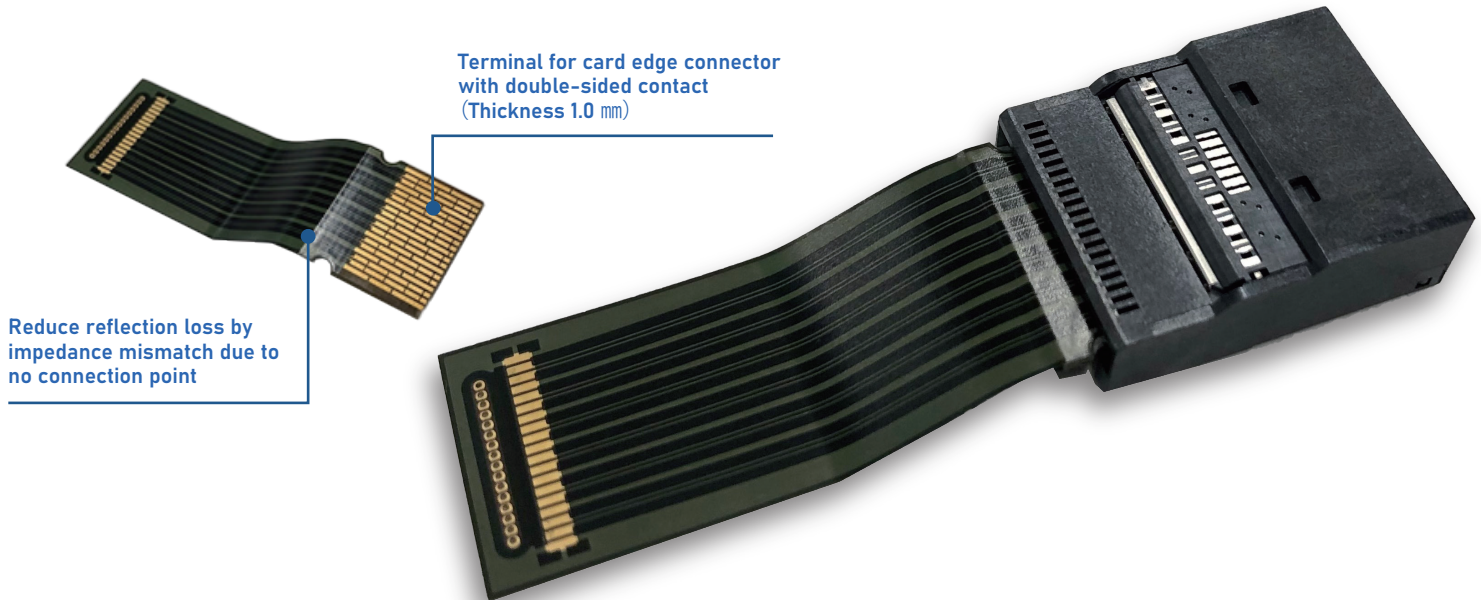


Separated multi-layer FPC for card edge

Multi-layer flexible board adaptable for fitting card edge connector with double-sided contact



An introduction video of this product is being released on Youtube



Product specification example

• Number of layers	: 4-6 layers
• Connection Via	: $\phi 0.1$ mm through via, $\phi 0.05$ mm blind Via
• Base material	: Polyimide (PI)
• FPC part thickness	: Approx 0.2 to 0.8 mm
• Card edge terminal thickness	: 1.0 mm
• Finish	: ENEPIG
• Impedance matching	: Differential $100\Omega \pm 8\%$, single $50\Omega \pm 8\%$

Product photo example

- Similar function as rigid flexible board and high reliability Via formation
- Stable impedance line can be formed due to integration of flexible board and rigid board and no connection point
- High density wiring with 100 μ m pitch wiring or Via land diameter of $\phi 300\mu$ m or less
- Bare chip wire bonding and BGA component mounting possible



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